



TAOGLAS®



Datasheet

Part No:

SDCP.5900.12.4.A.40

Description:

SDCP.5900 5.9GHz C-V2X Circular Polarized Embedded SMD 12*12*4mm Patch Antenna

Features:

5.9GHz C-V2X Ceramic Patch Antenna

5850MHz to 5925MHz

Peak Gain: 4.64dBi

Efficiency: 60%

Dimensions: 12*12*4mm

IATF16949 Production & Quality Approved

RoHS & REACH Compliant

| | |
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1. Introduction



The SDCP.5900.12.4.A.40 is a 12*12*4mm embedded ceramic C-V2X (& DSRC) Patch antenna. It is a high-performance directional antenna designed to operate at 5.9GHz for V2V / V2X / V2I systems. The directionality of the antenna allows further range of C-V2X communications. For example, one patch can be mounted to the front of the vehicle, and one to back. Its tiny size allows placement in crowded vehicle interiors. The SMD mounting is particularly suited to high volume manufacturing applications.

Typical Applications:

- Automotive Rearview Mirror Back Mount
- In-Vehicle Window Mount
- Embedded in Roadside Transceivers

C-V2X is the communications medium of choice for active safety V2V/V2X (Vehicle-to-Vehicle and Vehicle-to-Other) systems. Primarily allocated for vehicle safety applications, C-V2X supports high-speed, low-latency, short-range, V2V/V2X wireless communications.

The SDCP.5900 patch antenna has been designed to be circularly polarized to enable a more stable system signal strength typically required on moving vehicles. Circular polarization limits any potential drop in signal from orientation change to 3dB compared to a potential drop of 40dB or more for linear solutions. It results in a system that will maintain the communication link much more reliably.

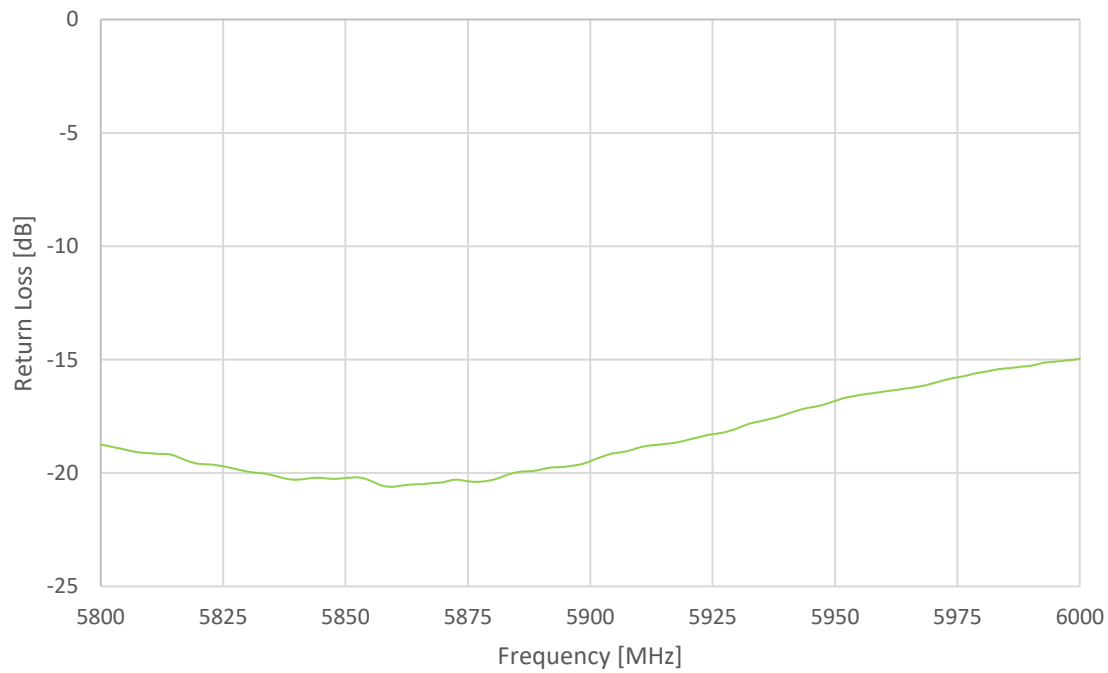
For further optimization to customer-specific device environments and for support to integrate and test this antennas performance in your device, contact your regional Taoglas customer support team.

2. Specifications

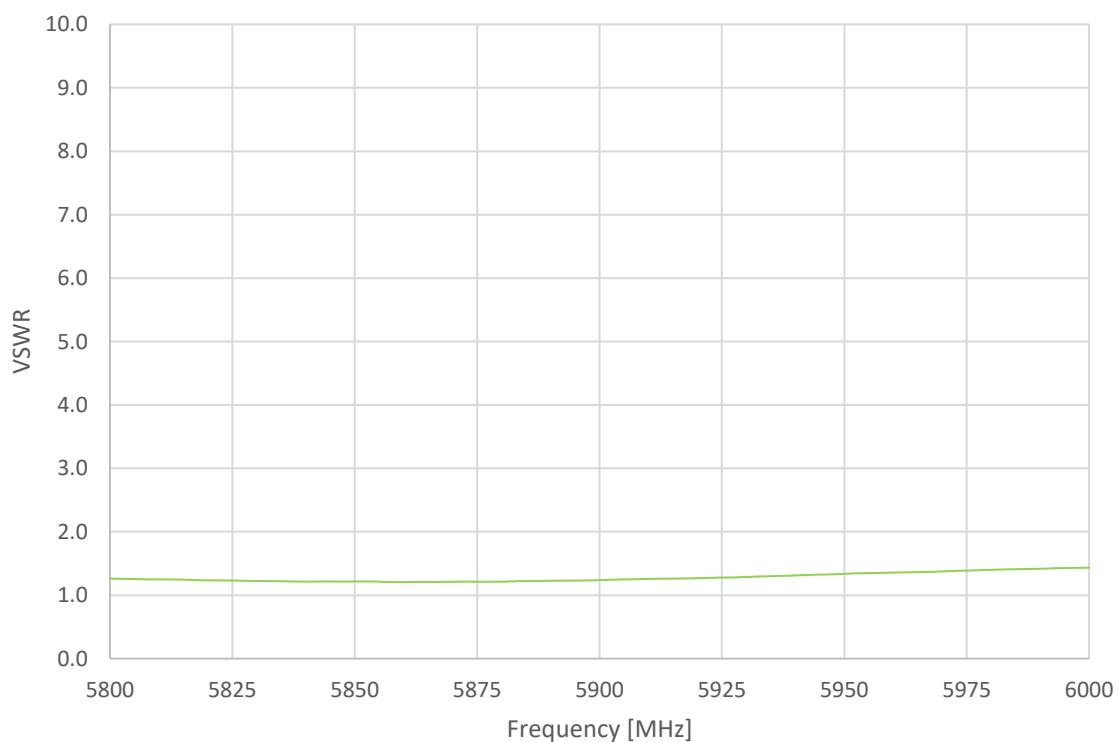
| Antenna | |
|----------------------------------|----------------------------|
| Frequency (MHz) | 5850~5925MHz |
| Efficiency | 60.45 % |
| Peak Gain | 4.64 dBi |
| Average Gain | -2.15 dBi |
| VSWR | < 2 |
| Polarization | RHCP |
| Axial Ratio | < 4 |
| Impedance (Ω) | 50 Ohms |
| Mechanical | |
| Dimensions (mm) | 12 x 12 x 4 |
| Weight | 2.0g |
| Mechanical | |
| Temperature Range | -40°C to 85°C |
| Humidity | Non-condensing 65°C 95% RH |
| Moisture Sensitivity Level (MSL) | 3 (168 Hours) |

3. Antenna Characteristics

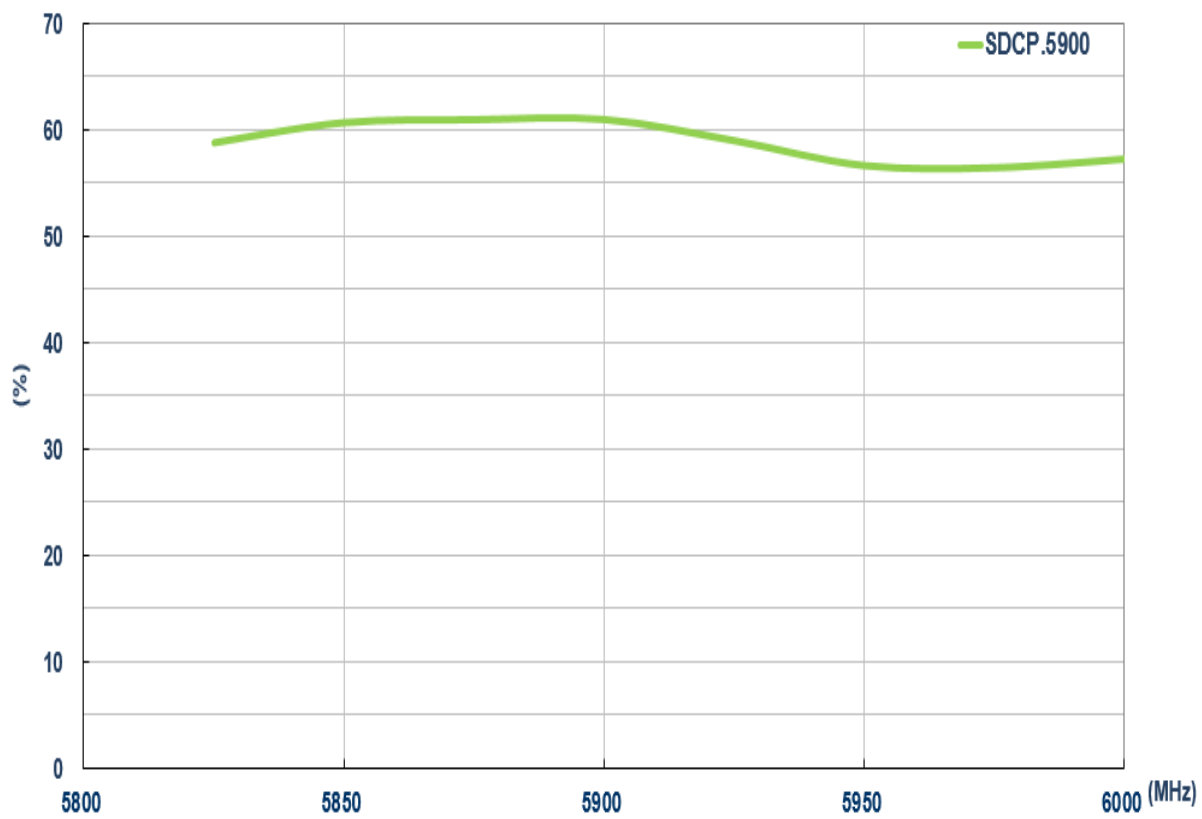
3.1 Return Loss



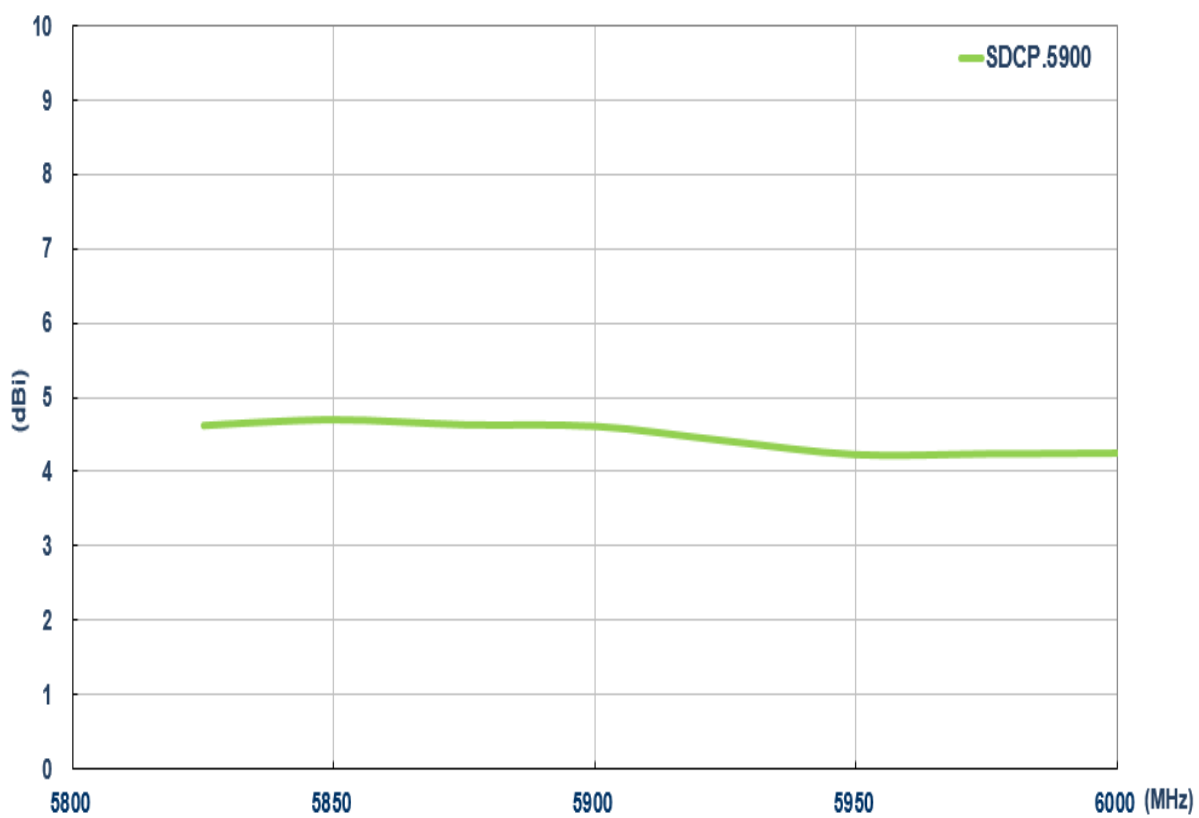
3.2 VSWR



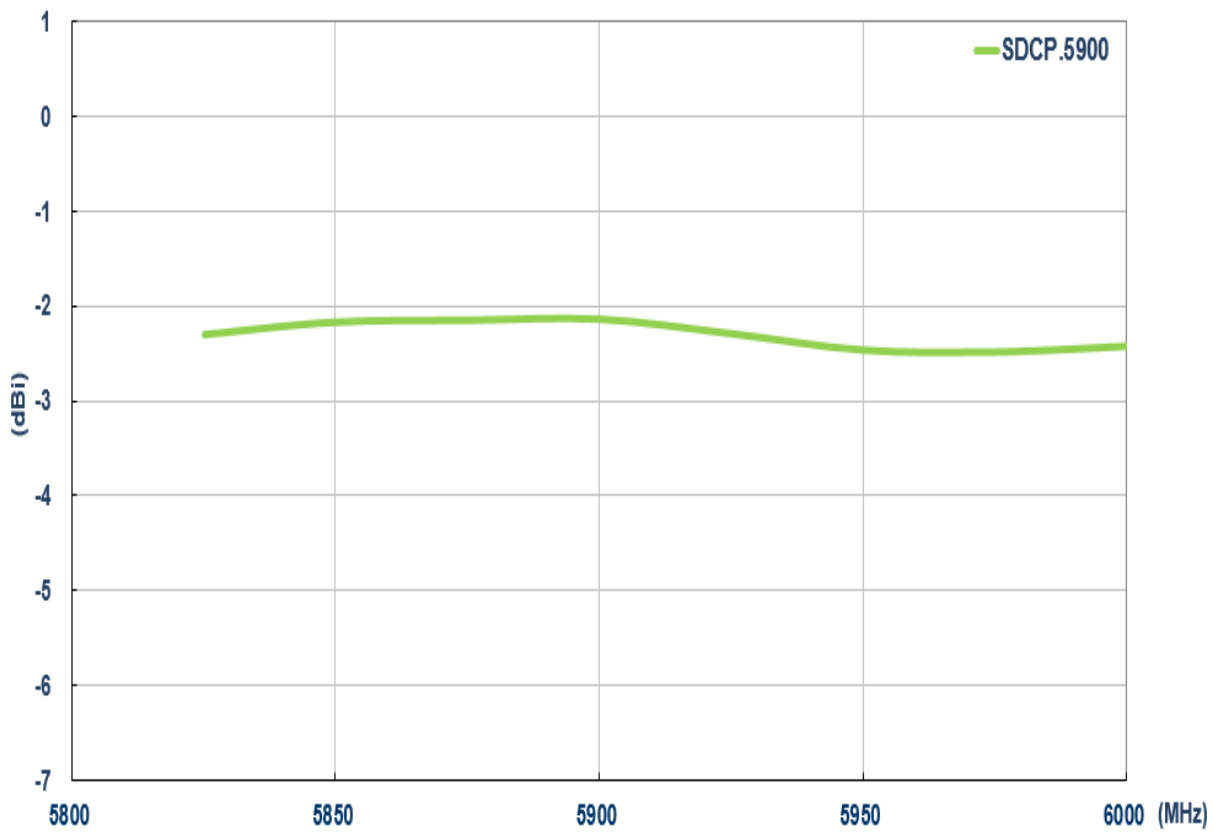
3.3 Efficiency



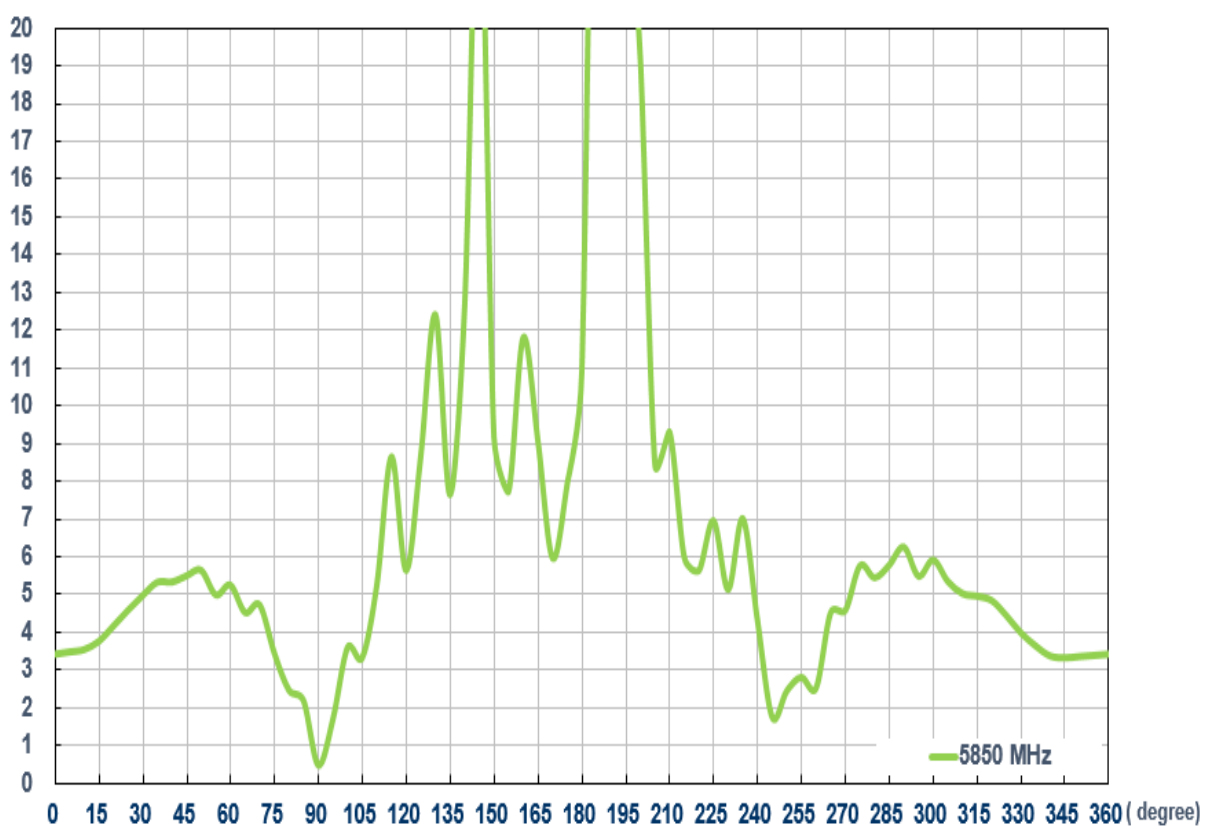
3.4 Peak Gain



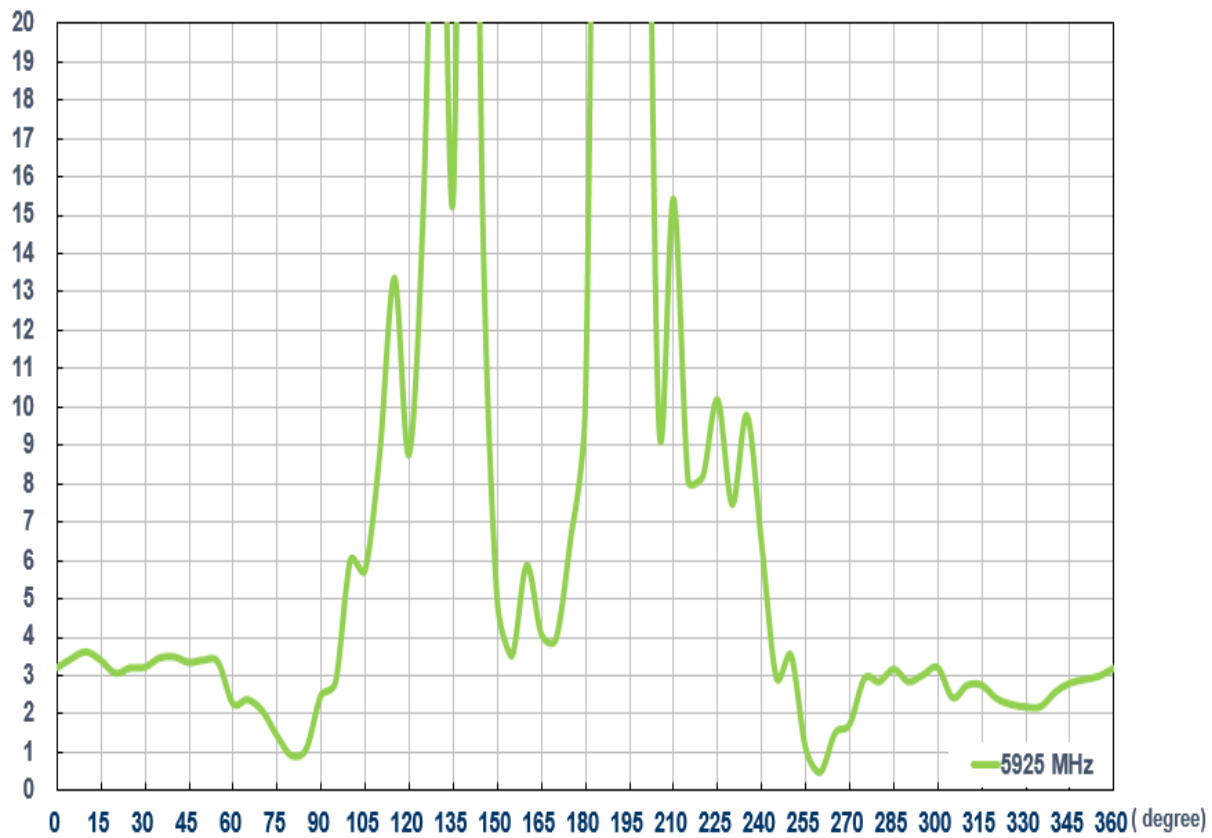
3.5 Average Gain



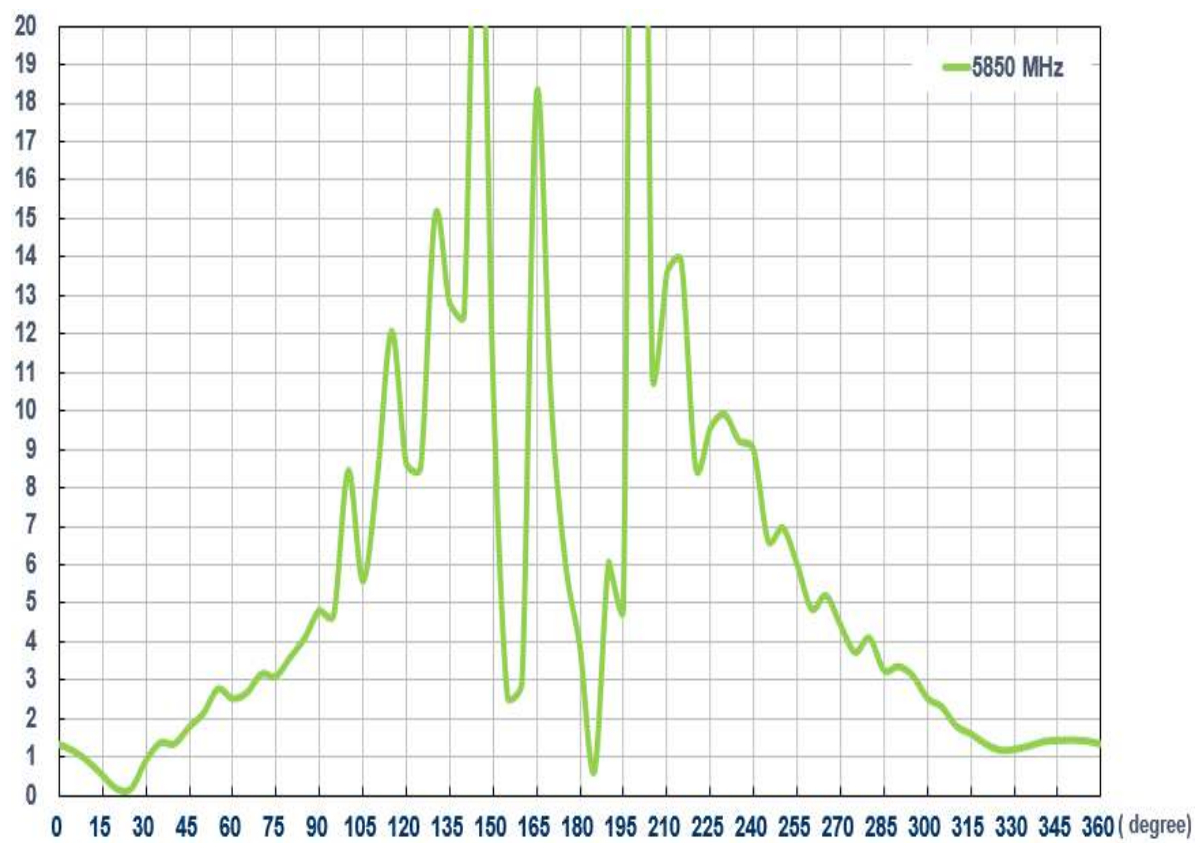
3.6 Axial Ratio: XZ Plane



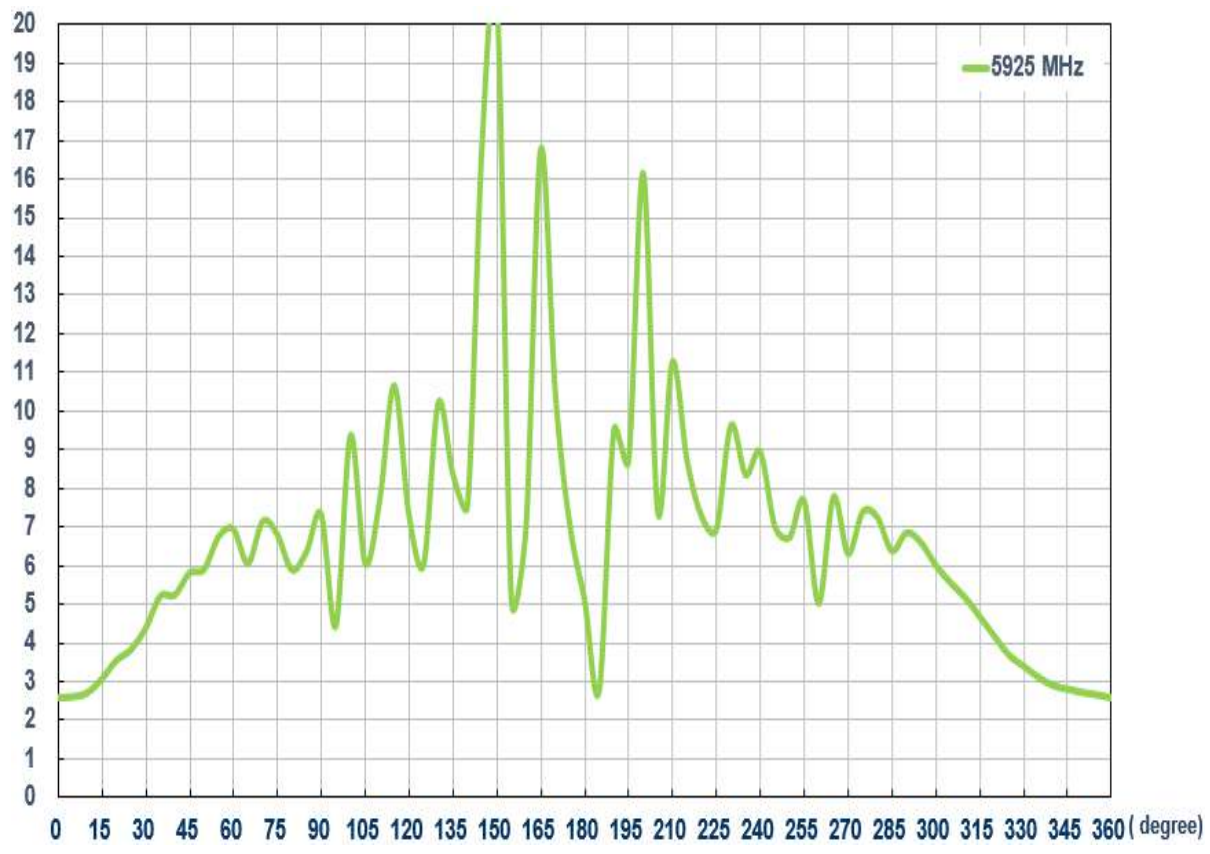
3.7 Axial Ratio: XZ Plane



3.8 Axial Ratio: YZ Plane

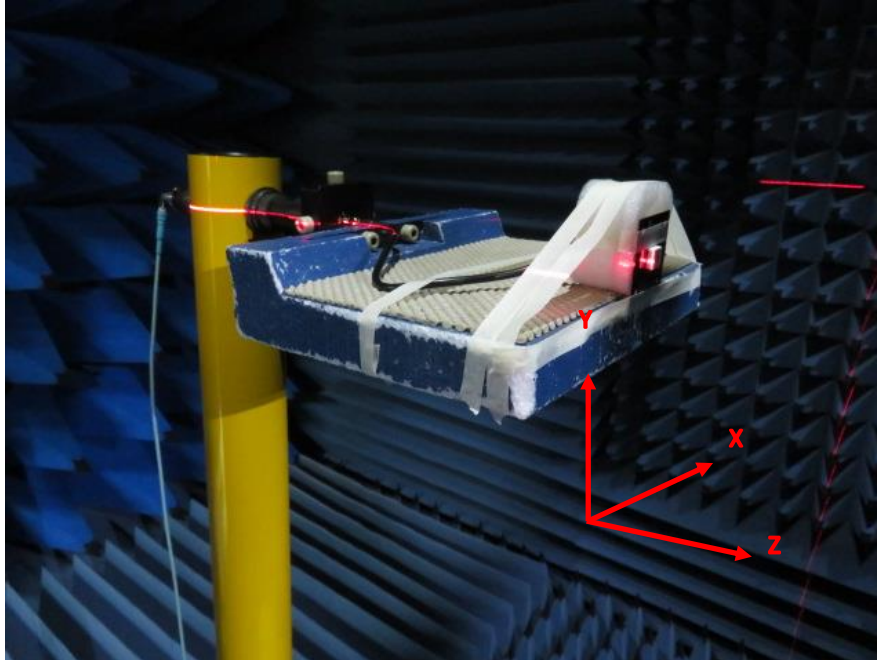


3.9 Axial Ratio: YZ Plane



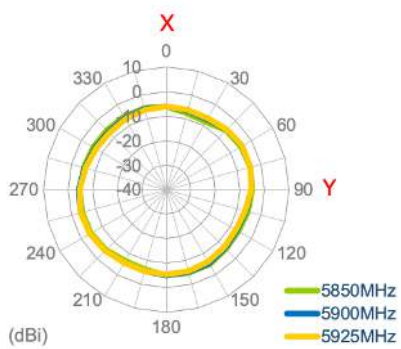
4. Radiation Patterns

4.1 Antenna Setup (Antenna testing Setup in ETS Anechoic Chamber)

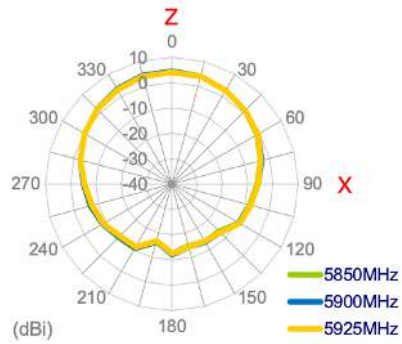


4.2 Radiation Patterns

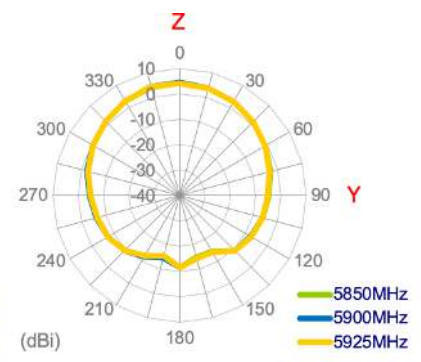
XY Plane



XY Plane Flipped

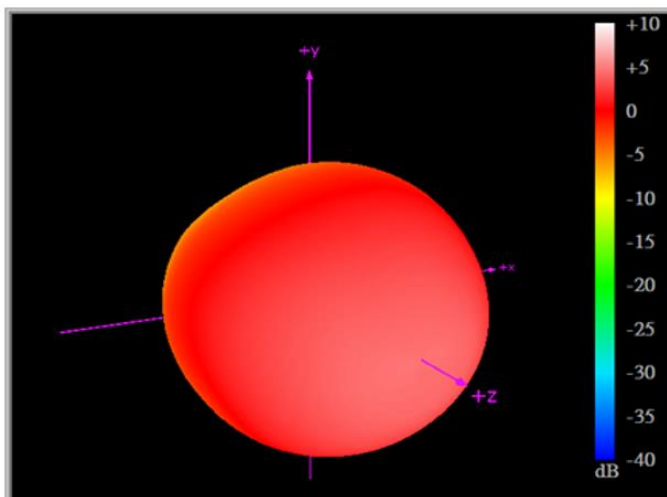


XZ Plane

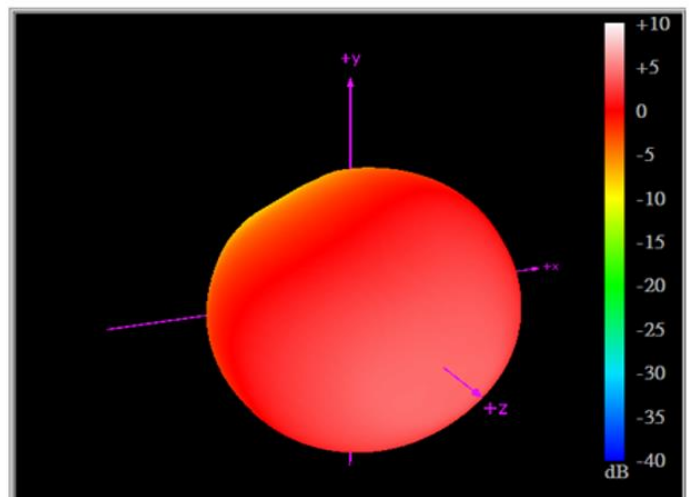


4.3 Antenna 3D Radiation Pattern (In free space)

5850MHz

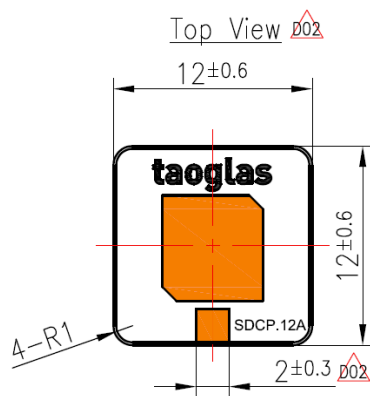


5925MHz



5. Mechanical Drawing - Antenna

5.1 Antenna Main Body

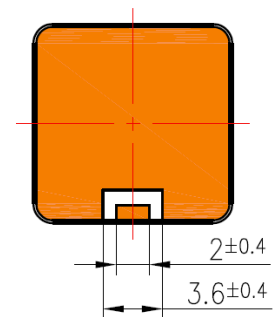


SCALE: 1/1

Side View



Bottom View



6. Footprint

6.1 Solder Land Pattern

| Foot Print | | | | | | | | | | | |
|--|---|-------------------|--|---------------------|--|----------------|--|---------------|--|------------------------|--|
| <p>Top Copper</p> <p>Pads 1, 2, 3, 4, 5, 6, 7 and 9 are the same size. They should be connected to GND.</p> | <p>Top Solder Paste</p> <p>Pads 1, 2, 3, 4, 5, 6, 7 and 9 are the same size.</p> | | | | | | | | | | |
| <p>Top Solder Mask</p> <p>Pads 1, 2, 3, 4, 5, 6, 7 and 9 are the same size. This drawing is a negative of solder mask. Black regions are anti-mask.</p> | <p>Composite Diagram</p> | | | | | | | | | | |
| <p>NOTE:</p> <table border="0"> <tr> <td>1. Ag Plated area</td> <td></td> </tr> <tr> <td>2. Solder Mask area</td> <td></td> </tr> <tr> <td>3. Copper area</td> <td></td> </tr> <tr> <td>4. Paste area</td> <td></td> </tr> <tr> <td>5. Copper Keepout Area</td> <td></td> </tr> </table> <p>6. Copper keepout should extend through all PCB layers. 7. Any vias in pads should be either filled or tented to prevent solder from wicking away from the pad during reflow. 8. The dimension tolerances should follow standard PCB manufacturing guidelines</p> | | 1. Ag Plated area | | 2. Solder Mask area | | 3. Copper area | | 4. Paste area | | 5. Copper Keepout Area | |
| 1. Ag Plated area | | | | | | | | | | | |
| 2. Solder Mask area | | | | | | | | | | | |
| 3. Copper area | | | | | | | | | | | |
| 4. Paste area | | | | | | | | | | | |
| 5. Copper Keepout Area | | | | | | | | | | | |

7. Antenna Integration Guide

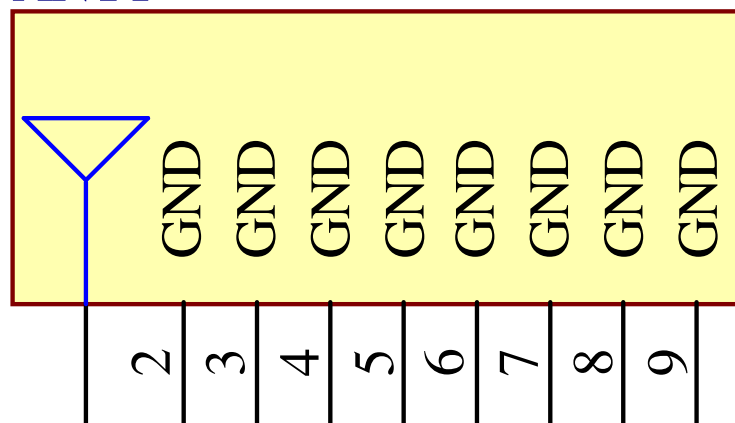


7.1 Schematic Symbol and Pin Definition

The circuit symbol for the antenna is shown below. The antenna has 9 pins as indicated below.

| Pin | Description |
|------------------------|-------------|
| 1 | RF Feed |
| 2, 3, 4, 5, 6, 7, 8, 9 | Ground |

SDCP.5900.12.4.A40
ANT1

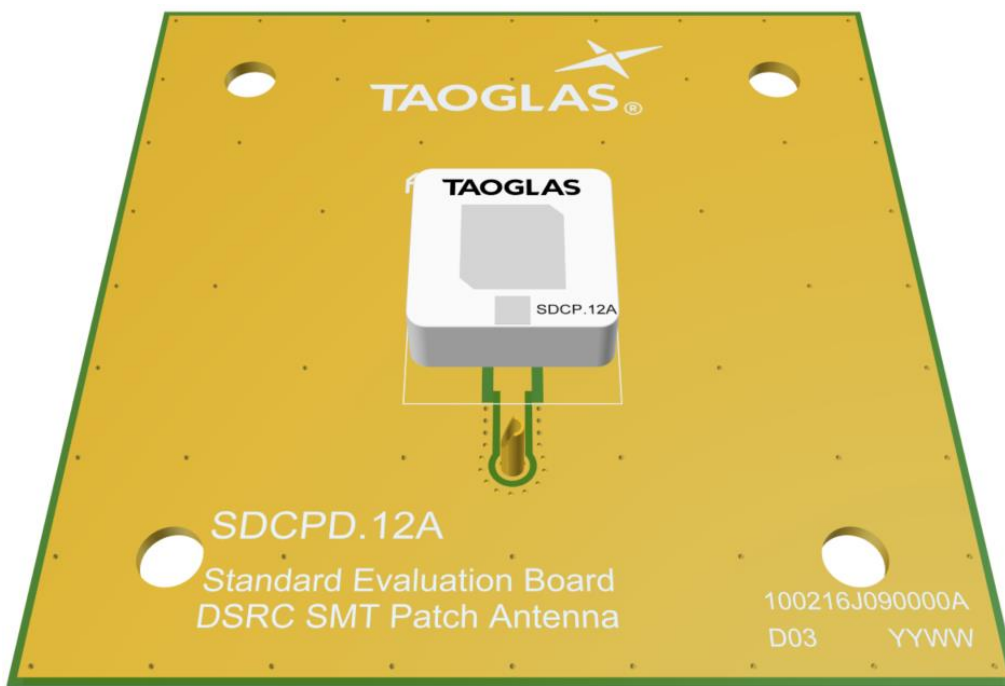


7.2 Antenna Integration

The antenna should be placed at the center of the ground plane with a length and width of 50mm. Maintaining a square symmetric ground plane shape and symmetric environment around the antenna is critical to maintaining the excellent axial ratio and phase center performance shown in this datasheet.



Top Side w/ Solder Mask



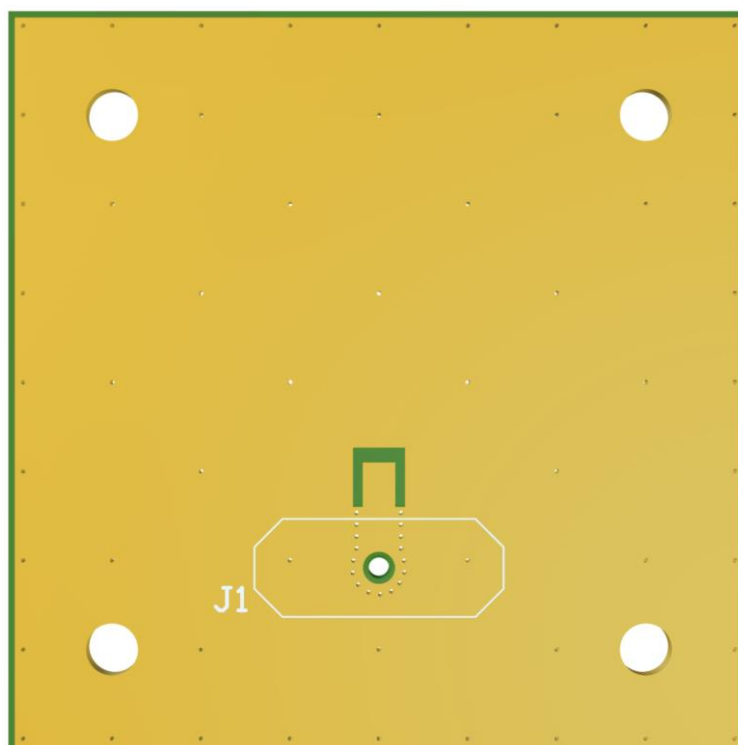
Top Side w/o Solder Mask

7.3 PCB Layout

The footprint and clearance on the PCB must comply with the antenna specification. The PCB layout shown in the diagram below demonstrates the antenna footprint.



Topside

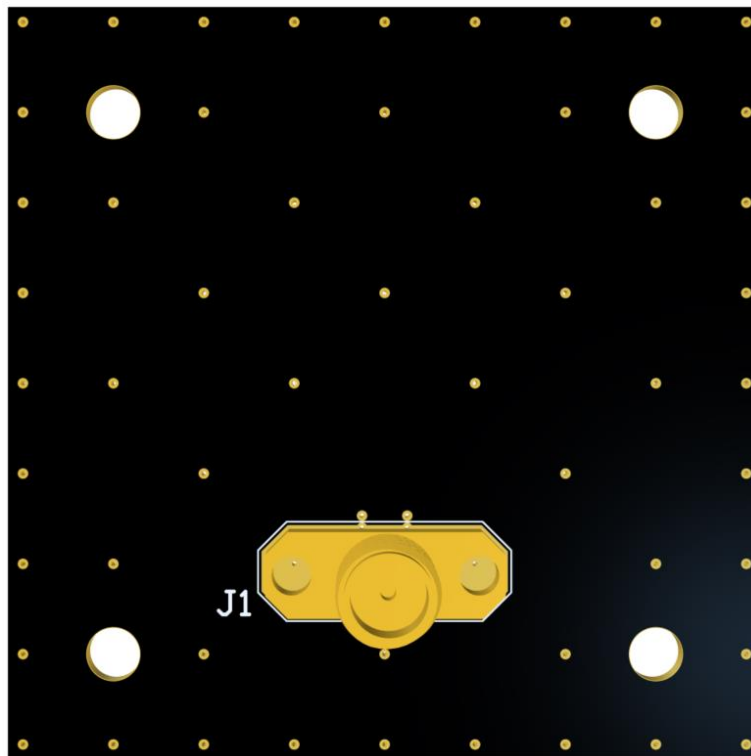


Bottom Side

7.4 Evaluation Board

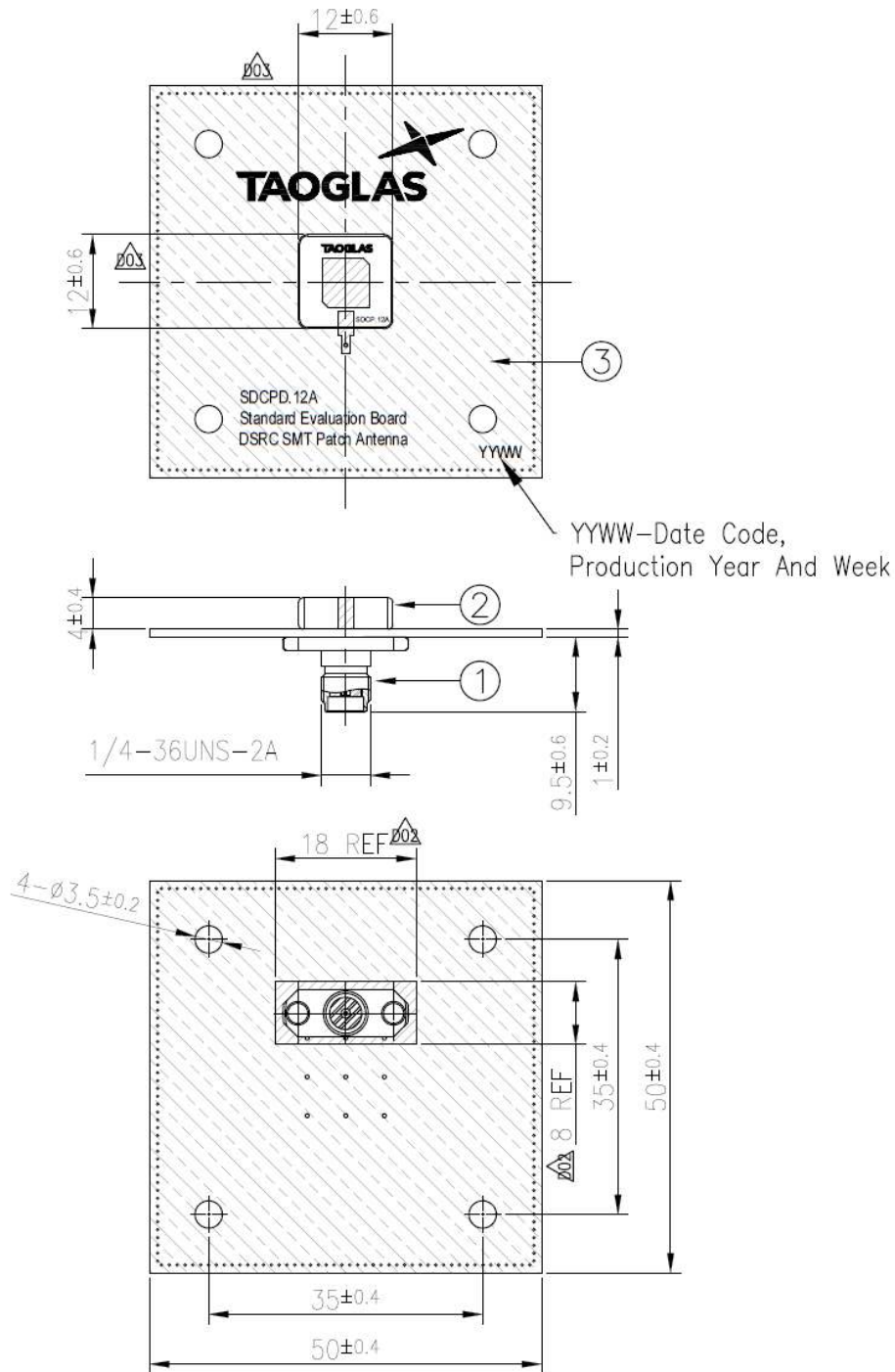


Topside



Bottom Side

8. Mechanical Drawing – Evaluation Board



Note:

- 1. Silver Area
- 2. Soldermask Area
- 3. Logo & Text Ink Printing : White

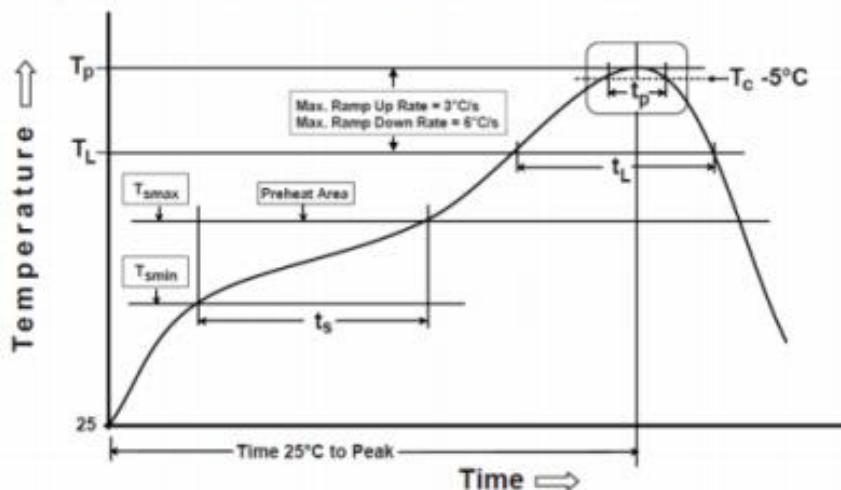
| | Name | P/N | Material | Finish | QTY |
|---|--------------------------------|----------------|----------------|-----------|-----|
| 1 | PCB SMA(F)ST $\varnothing 0.3$ | 001516J000000A | Brass | Au Plated | 1 |
| 2 | SDCP.12A Patch(12x12x4mm) | 001516J000000A | Ceramic | Clear | 1 |
| 3 | SDCPD.12A PCB | 100216J090000A | Composite 1.0t | Black | 1 |

9. Soldering Conditions

SDCP.5900.12A can be assembled following Pb-free assembly. According to the Standard IPC/JEDEC J-STD-020C, the temperature profile suggested is as follows:

| Phase | Profile Features | Pb-Free Assembly (SnAgCu) |
|------------------------------------|---|----------------------------------|
| PREHEAT | Temperature Min(T_{smin}) Temperature Max(T_{smax}) Time(t_s) from (T_{smin} to T_{smax}) | 150°C 200°C 60-120 seconds |
| RAMP-UP | Avg. Ramp-up Rate (T_{smax} to TP) | 3°C/second(max) |
| REFLOW | Temperature(T_L) Total Time above T_L (t_L) | 217°C 30-100 seconds |
| PEAK | Temperature(T_P) Time(t_p) | 260°C 2-5 seconds |
| RAMP-DOWN | Rate | 3°C/second(max) |
| Time from 25°C to Peak Temperature | | 8 minutes max. |
| Composition of solder paste | | 96.5Sn/3Ag/0.5Cu |
| Solder Paste Model | | SHENMAO PF606-P26 |

The graphic shows temperature profile for component assembly process in reflow ovens

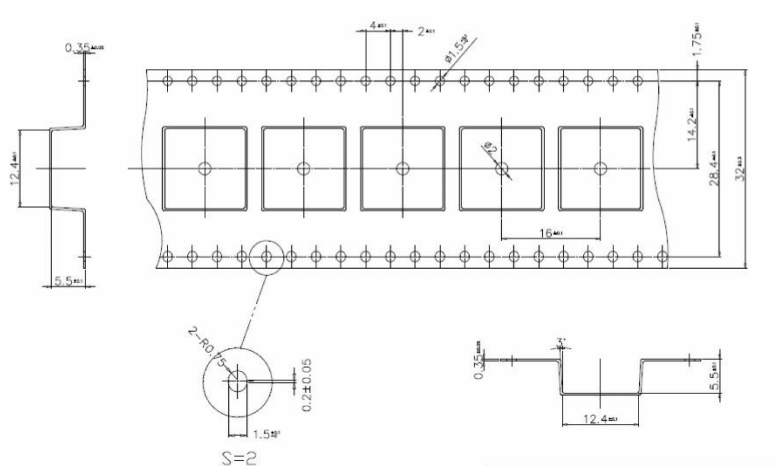
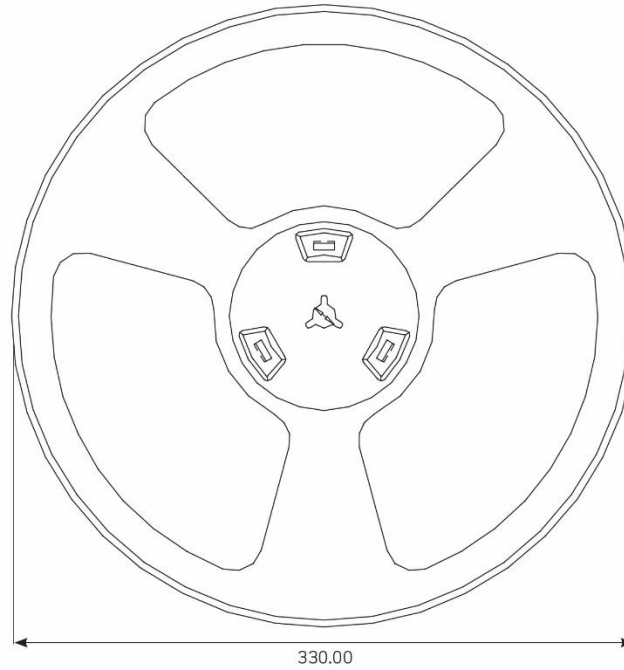


Soldering iron condition: Soldering iron temperature $270^\circ\text{C} \pm 10^\circ\text{C}$.

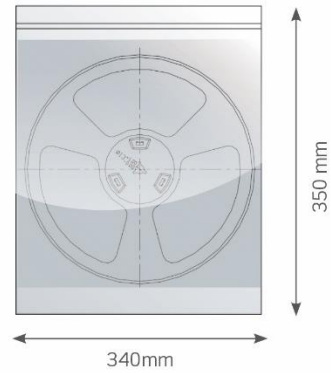
Apply preheating at 120°C for 2-3 minutes. Finish soldering for each terminal within 3 seconds, if soldering iron temperature over $270^\circ\text{C} \pm 10^\circ\text{C}$ or 3 seconds, it will make cause component surface peeling or damage.

10. Packaging

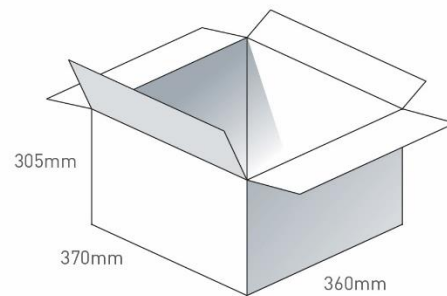
500 pc SDCP.5900.12.4.A.40 per reel
 Dimensions - Ø330*55mm
 Weight - 2300g



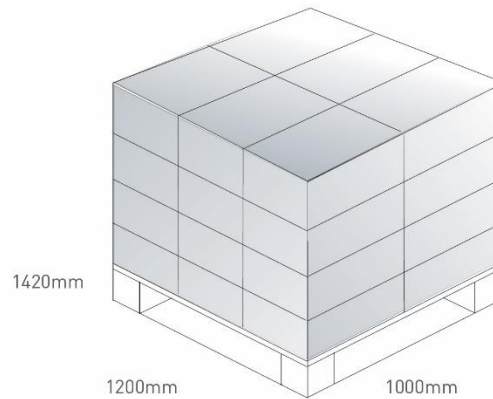
1 pc reel in small in Anti-static Bag
 Dimensions - 340*350*70mm
 Weight - 2400g



4 Reels in Anti-static Bags
 2000 pcs in one carton
 Carton Dimensions - 370*360*305mm
 Weight - 10.5Kg



Pallet Dimensions 1200*1000*1420mm
 24 Cartons per Pallet
 6 Cartons per layer
 4 Layers



Changelog for the datasheet

SPE-17-8-037– SDCP.5900.12.4.A.40

Revision: E (Current Version)

| | |
|------------------|---------------------------------|
| Date: | 2021-10-05 |
| Changes: | Antenna Integration Guide Added |
| Changes Made by: | Cesar Sousa |

Previous Revisions

Revision: D

| | |
|------------------|---------------------------------|
| Date: | 2021-10-05 |
| Changes: | Updated VNA measurement graphs. |
| Changes Made by: | Gary West |

Revision: C

| | |
|------------------|--------------------|
| Date: | 2021-10-05 |
| Changes: | Format Change, MSL |
| Changes Made by: | Erik Landi |

Revision: B

| | |
|------------------|------------------|
| Date: | 2021-10-25 |
| Changes: | Updated to C-V2X |
| Changes Made by: | Jack Conroy |

Revision: A (Original First Release)

| | |
|---------|-----------------|
| Date: | 2017-7-12 |
| Notes: | Initial Release |
| Author: | STAFF |



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